### 502339705 05/08/2013

#### PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
Koya MUYARI	03/29/2013
Koji ITO	03/29/2013
Atsushi OGASAWARA	03/29/2013
Kazuhiko ITO	03/29/2013

#### RECEIVING PARTY DATA

Name:	SHINDENGEN ELECTRIC MANUFACTURING CO., LTD.
Street Address:	2-1, Otemachi 2-chome, Chiyoda-ku,
City:	Tokyo
State/Country:	JAPAN
Postal Code:	100-0004

#### PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13883916

### CORRESPONDENCE DATA

Fax Number: 7035185499

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: 703-684-1111
Email: bjhgroup@ipfirm.com

Correspondent Name: Lowe Hauptman Ham & Berner, LLP

Address Line 1: 2318 Mill Road, Suite 1400
Address Line 4: Alexandria, VIRGINIA 22314

ATTORNEY DOCKET NUMBER:	4592-032
NAME OF SUBMITTER:  Benjamin J. Hauptman	
Signature:	/Benjamin J. Hauptman/
Date:	05/08/2013

Total Attachments: 1

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PATENT REEL: 030374 FRAME: 0650 OF \$40.00 13883916

Docket No.: 4592-032

### ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

1) Koya MUYARI

Kazuhiko ITO

- 2) Koji ITO
- 3) Atsushi OGASAWARA

who has made a certain new and useful invention, hereby sells, assigns and transfers unto

# SHINDENGEN ELECTRIC MANUFACTURING CO., LTD. having a place of business at 2-1, Otemachi 2-chome, Chivoda-ku, Tokyo 100-0004 Japan its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled GLASS COMPOSITION FOR PROTECTING SEMICONDUCTOR JUNCTION, METHOD OF

## MANUFACTURING SEMICONDUCTOR DEVICE AND SEMICONDUCTOR DEVICE

a)	for which an application for United States Letters Patent was filed on,	and	identified	by
	United States Patent Application No; or			
b)	for which an application for United States Letters Patent was executed on,			

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

1) Koya MUYARI	March 29,2013
Name: Koya MUYARI	Date:
2) <u>Kojć Ito</u> Name: <b>Koji ITO</b>	March 29, 2013
Name: Koji ITO	Date:
3) atsushi Ogasamara	March 29, 2013
Name: Atsushi OGASAWARA	Date:
4) Mazohiho Ito	march 29, 2013
Name: Kazuhiko ITO	Date:

PATENT REEL: 030374 FRAME: 0651

RECORDED: 05/08/2013